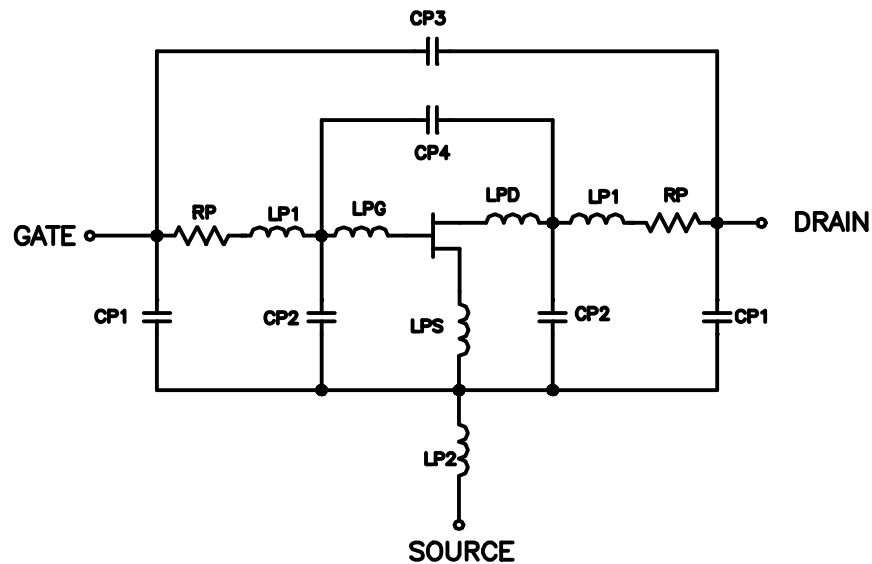




Shown below is an approximate model for use with packaged FETs. The FET shown in the schematic can be replaced with the small signal or large signal model for the chip, including bond wire inductances. The element values shown below for the various packages provide a first order approximation, as the exact values will vary depending on the device type.



Parameter	Units	SOT-89	70 mil	100 mil flange	180 mil flange	CP083
CP1	pF	0.28	0.038	0.05	0.78	0.52
CP2	pF	0.39	0.13	0.2	0.57	0
LP1	nH	1.2	0.25	0.5	0.61	0.56
RP	ohm	0	0.7	0.8	0	0
CP3	pF	0	0.006	0	0	0
CP4	pF	0.3	0	0	0	0
LPG	nH	0	0.3	0.14	0.34	0.06
LPD	nH	0	0.2	0.1	0.2	0.2
LPS	nH	0.009	0.028	0	0.017	0.018
LP2	nH	0	0.065	0.03	0	0